

ABSTRACT OF THE DISCLOSURE

SEMICONDUCTOR CUTTING DEVICE, SEMICONDUCTOR CUTTING METHOD, SEMICONDUCTOR CUTTING SYSTEM, LASER CUTTING 5 DEVICE AND LASER CUTTING METHOD

A semiconductor cutting apparatus is disclosed which is capable of reducing an inclination of a cutting section by a laser beam of a semiconductor substrate without extending the distance from the semiconductor substrate to a laser scanning center. The apparatus includes a laser oscillator, a transport mechanism causing a semiconductor substrate and the laser oscillator to relatively move, and a controller controlling the laser oscillator and the transport mechanism. When a plurality of semiconductor device regions each being surrounded by a predetermined cutting line are provided in the semiconductor substrate, the controller controls the transport mechanism such that a scanning center of the laser beam of the laser oscillator is located above a position inner than the predetermined cutting line of each semiconductor device region and causes the laser oscillator to perform the scanning of the laser beam along the predetermined cutting line of the semiconductor device region.

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Fig. 1